



### **Dual N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
	11.5mΩ @ V <sub>GS</sub> = 4.5V	10 A
20V	14mΩ @ V <sub>GS</sub> = 2.5V	9 A

### **Description**

This new generation MOSFET has been designed to minimize the onstate resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

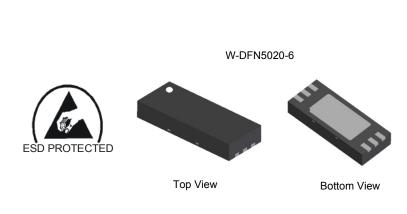
- General Purpose Interfacing Switch
- **Power Management Functions**

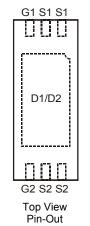
## **Features and Benefits**

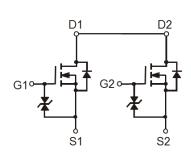
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected**
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: W-DFN5020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.03 grams (approximate)







**Equivalent Circuit** 

### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2013UFX-7	W-DFN5020-6	3000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.htmlfor more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



FX = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010)M = Month (ex: 9 = September)

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Date Code ite												
Year	201	0	2011		2012	20	13	2014		2015	2	2016
Code	X		Υ		Z	A	4	В		С		D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteris	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±8	V		
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	10 8	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 2.5V	I <sub>D</sub>	9 7	А		
Pulsed Drain Current (Note 7)	I <sub>DM</sub>	80	Α		

## **Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	$P_{D}$	0.78	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 5)	$R_{\theta JA}$	163	°C/W
Power Dissipation (Note 6)	P <sub>D</sub>	2.14	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 6)	$R_{\theta JA}$	59	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

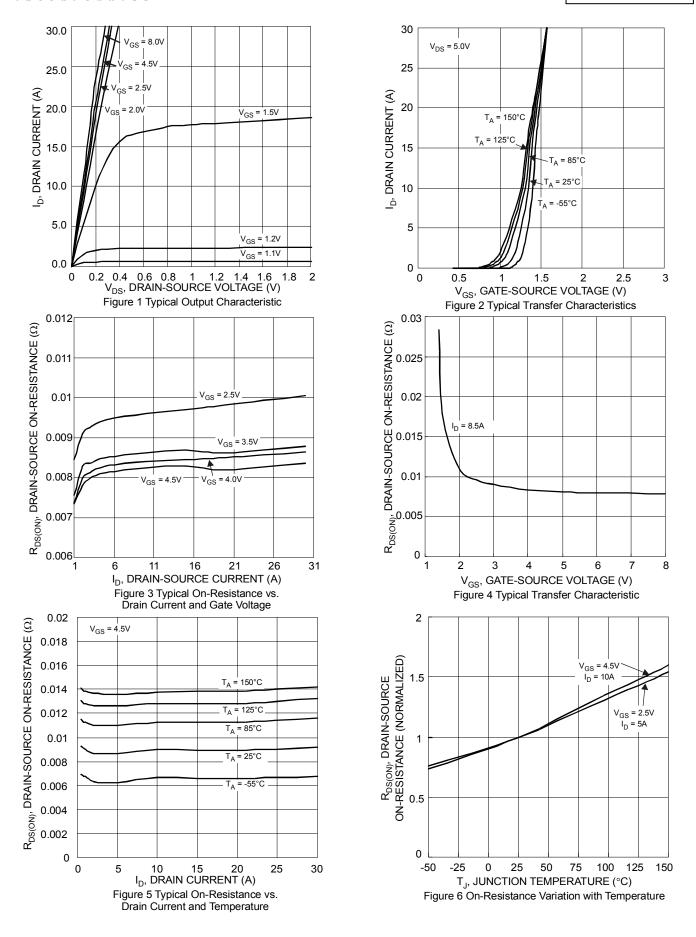
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
DFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_		V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>		_	1	μΑ	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>		_	±10	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)						_	
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	_	1.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			8.4	11.5		$V_{GS} = 4.5V$ , $I_D = 8.5A$	
			8.5	12.0		$V_{GS} = 4.0V, I_D = 8.5A$	
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	8.6	12.5	mΩ	$V_{GS} = 3.5V, I_D = 8.5A$	
			9.0	13.5		$V_{GS} = 3.1V, I_D = 8A$	
			9.6	14.0		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 8A	
Forward Transfer Admittance	Y <sub>fs</sub>	_	18.2	_	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 4A	
Diode Forward Voltage	$V_{SD}$	_	_	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 8.5A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	1	2607	_	pF	\\ - 40\\ \\ - 0\\	
Output Capacitance	Coss	I	255		рF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1 0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	l	236		рF	1 - 1.000112	
Gate Resistance	$R_{g}$	I	1.2		Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg		32.4		nC		
Total Gate Charge (V <sub>GS</sub> = 8V)	Qg	_	57.4	_	nC	V - 10V I - 9.5A	
Gate-Source Charge	Q <sub>gs</sub>	_	3.5	_	nC	$V_{DS} = 10V, I_D = 8.5A$	
Gate-Drain Charge	$Q_{gd}$	_	4.0	_	nC	]	
Turn-On Delay Time	t <sub>D(on)</sub>	_	8.6	_	ns		
Turn-On Rise Time	t <sub>r</sub>	_	20.3	_	ns	V <sub>DS</sub> = 10V, I <sub>D</sub> = 8.5A	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	42.5	_	ns	$V_{GS} = 4.5V, R_G = 1.8\Omega$	
Turn-Off Fall Time	t <sub>f</sub>		13.7	_	ns		

Notes:

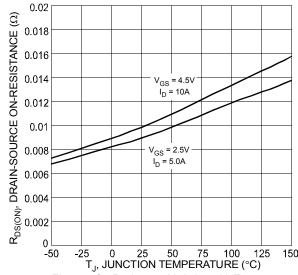
- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate
- 7. Repetitive rating, pulse width limited by junction temperature.
- 8. Short duration pulse test used to minimize self-heating effect.
- Guaranteed by design. Not subject to production testing.

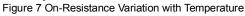
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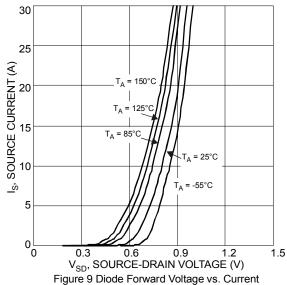


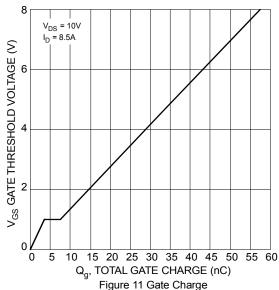












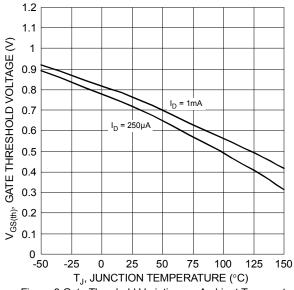
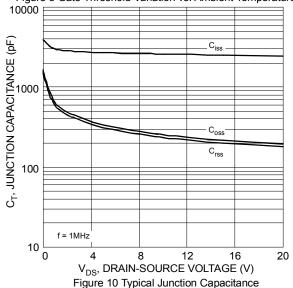


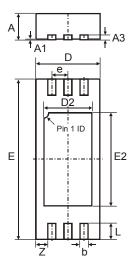
Figure 8 Gate Threshold Variation vs. Ambient Temperature





# **Package Outline Dimensions**

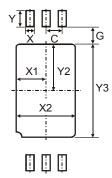
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



W-DFN5020-6							
Dim	Min	Max	Тур				
Α	0.75	0.85	0.80				
A1	0	0.05	0.02				
А3	-	-	0.15				
b	0.20	0.30	0.25				
D	1.90	2.10	2.00				
D2	1.40	1.60	1.50				
е	-	_	0.50				
Е	4.90	5.10	5.00				
E2	2.80	3.00	2.90				
L	0.35	0.65	0.50				
Z	-	-	0.375				
All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.50
G	0.35
Х	0.35
X1	0.90
X2	1.80
Υ	0.70
Y2	1.60
Y3	3.20



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